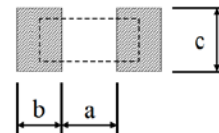
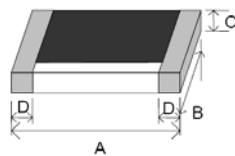


**A. Electrical Specifications:**

Part No.	L (nH)	Tolerance	Q Min.	SRF Min. (GHz)	DCR Max. (Ω)	I DC Max. (mA)
0201TF-N10	0.1	B, C, S	8/500MHz	9	0.20	400
0201TF-N20	0.2	B, C, S	8/500MHz	9	0.20	400
0201TF-N30	0.3	B, C, S	8/500MHz	9	0.20	400
0201TF-N40	0.4	B, C, S	8/500MHz	9	0.25	350
0201TF-N50	0.5	B, C, S	8/500MHz	9	0.25	350
0201TF-N60	0.6	B, C, S	8/500MHz	9	0.25	350
0201TF-N70	0.7	B, C, S	8/500MHz	9	0.30	300
0201TF-N80	0.8	B, C, S	8/500MHz	9	0.30	300
0201TF-N90	0.9	B, C, S	8/500MHz	9	0.30	300
0201TF-1N0	1.0	B, C, S	8/500MHz	9	0.30	300
0201TF-1N1	1.1	B, C, S	8/500MHz	9	0.35	300
0201TF-1N2	1.2	B, C, S	8/500MHz	9	0.35	300
0201TF-1N3	1.3	B, C, S	8/500MHz	9	0.45	250
0201TF-1N4	1.4	B, C, S	8/500MHz	9	0.45	250
0201TF-1N5	1.5	B, C, S	8/500MHz	9	0.45	250
0201TF-1N6	1.6	B, C, S	8/500MHz	9	0.55	200
0201TF-1N7	1.7	B, C, S	8/500MHz	9	0.55	200
0201TF-1N8	1.8	B, C, S	8/500MHz	9	0.55	200
0201TF-1N9	1.9	B, C, S	8/500MHz	9	0.55	200
0201TF-2N0	2.0	B, C, S	8/500MHz	8	0.70	200
0201TF-2N1	2.1	B, C, S	8/500MHz	8	0.70	200
0201TF-2N2	2.2	B, C, S	8/500MHz	8	0.70	200
0201TF-2N3	2.3	B, C, S	8/500MHz	8	0.80	150
0201TF-2N4	2.4	B, C, S	8/500MHz	8	0.80	150
0201TF-2N5	2.5	B, C, S	8/500MHz	8	0.80	150
0201TF-2N6	2.6	B, C, S	8/500MHz	8	0.80	150
0201TF-2N7	2.7	B, C, S	8/500MHz	8	0.80	150
0201TF-2N8	2.8	B, C, S	8/500MHz	6	1.00	150
0201TF-2N9	2.9	B, C, S	8/500MHz	6	1.00	150
0201TF-3N0	3.0	B, C, S	8/500MHz	6	1.00	150
0201TF-3N1	3.1	B, C, S	8/500MHz	6	1.00	150
0201TF-3N2	3.2	B, C, S	8/500MHz	6	1.00	150
0201TF-3N3	3.3	B, C, S	8/500MHz	6	1.00	150
0201TF-3N4	3.4	B, C, S	8/500MHz	6	1.20	150
0201TF-3N5	3.5	B, C, S	8/500MHz	6	1.20	150
0201TF-3N6	3.6	B, C, S	8/500MHz	6	1.20	150
0201TF-3N7	3.7	B, C, S	8/500MHz	6	1.20	150
0201TF-3N8	3.8	B, C, S	8/500MHz	6	1.20	150
0201TF-3N9	3.9	B, C, S	8/500MHz	6	1.20	150
0201TF-4N0	4.0	B, C, S	8/500MHz	6	1.20	150
0201TF-4N4	4.4	B, C, S	8/500MHz	6	1.30	140
0201TF-4N7	4.7	B, C, S	8/500MHz	6	1.40	130
0201TF-4N9	4.9	B, C, S	8/500MHz	6	1.60	130
0201TF-5N6	5.6	G, J	8/500MHz	4	1.80	130
0201TF-6N1	6.1	G, J	8/500MHz	4	2.00	120
0201TF-6N8	6.8	G, J	8/500MHz	4	2.30	110
0201TF-7N4	7.4	G, J	8/500MHz	4	2.80	110
0201TF-8N2	8.2	G, J	8/500MHz	3	3.00	110
0201TF-9N1	9.1	G, J	8/500MHz	3	3.25	100
0201TF-9N2	9.2	G, J	8/500MHz	3	3.25	100
0201TF-10N	10.0	G, J	8/500MHz	2	3.50	80

**B. Dimensions and Recommend Land Pattern: (mm/Inch)**

Series	A	B	C	D	a	b	c
0201TF	0.60±0.05 (0.024±0.002)	0.30±0.05 (0.012±0.002)	0.23±0.05 (0.009±0.002)	0.15±0.05 (0.006±0.002)	0.30 (0.0118)	0.25 (0.010)	0.30±0.20 (0.0118±0.008)



Recommend Land Pattern

**C. Part Number (Example):**



**D. General information:**

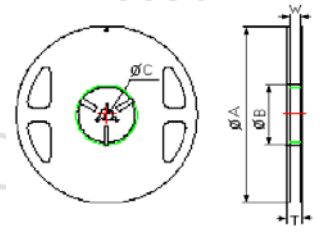
- 0201TF-xxx, "0201TF" = P/N, "xxx" = Inductance, "-" = Tolerance.
- Tolerance "-": J:  $\pm 5\%$ , H:  $\pm 3\%$ , G:  $\pm 2\%$ , F:  $\pm 1\%$ , B:  $\pm 0.1\text{nH}$ , C:  $\pm 0.2\text{nH}$ , S:  $\pm 0.3\text{nH}$ .
- A Photo Lithographic Single Layer Ceramic Chip.
- High SRF, Excellent Q, Superior Temperature Stability
- Tight Tolerance of  $\pm 1\%$  or  $\pm 0.1\text{nH}$
- Stable Inductance in High Frequency Circuit
- Maximum Temperature Rise:  $15^\circ\text{C}$  (when measured at  $25^\circ\text{C}$  ambient).
- Inductance & Q measured using the HP4286A and Agilent 16196B.
- SRF measured using the HP8720D or HP8753E.
- DCR measured using the 502BC.
- Operating temperature:  $-40^\circ\text{C}$  to  $+125^\circ\text{C}$ .
- Storage Temperature:  $25^\circ\text{C} \pm 3^\circ\text{C}$ ; Humidity  $< 80\% \text{RH}$
- Inductance Range: 0.10 nH (400 mA) ~ 10.0 nH (80 mA), SRF from 9.0 GHz to 2.0 GHz.
- MSL: Level 1.

**E. Applications:**

- Cellular-phone, Pagers and GPS Products.
- VCO, TCXO Circuit and RF Transceiver Module.
- Wireless LAN, Bluetooth Module, Communication Appliances Hybrid.

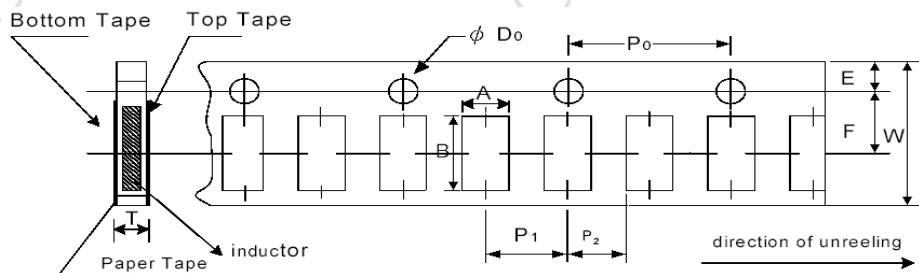
**F. Reel Specification:**

Series	$\phi A$	$\phi B$	$\phi C$	W	T	Quantity
0201TF	178 $\pm$ 1 (7 $\pm$ 0.040)	60 $\pm$ 1.0 (0.236 $\pm$ 0.040)	13.5 $\pm$ 0.70 (0.531 $\pm$ 0.028)	9.5 $\pm$ 1.0 (0.374 $\pm$ 0.040)	11.5 $\pm$ 1.0 (0.453 $\pm$ 0.040)	10,000 PCS



**G. Paper Tape Specification:**

Series	A	B	W	E	F	Po	P1	P2	$\phi Do$	T
0201TF	0.40 $\pm$ 0.05 (0.016 $\pm$ 0.002)	0.70 $\pm$ 0.05 (0.028 $\pm$ 0.002)	8.00 $\pm$ 0.10 (0.315 $\pm$ 0.004)	1.75 $\pm$ 0.05 (0.069 $\pm$ 0.002)	3.50 $\pm$ 0.05 (0.138 $\pm$ 0.002)	4.00 $\pm$ 0.10 (0.158 $\pm$ 0.004)	2.00 $\pm$ 0.05 (0.079 $\pm$ 0.002)	2.00 $\pm$ 0.05 (0.079 $\pm$ 0.002)	1.55 $\pm$ 0.05 (0.061 $\pm$ 0.002)	0.42 $\pm$ 0.02 (0.017 $\pm$ 0.0008)



**Tape & Reel Storage Temperature:  $25^\circ\text{C} \pm 3^\circ\text{C}$ , Humidity:  $< 80\% \text{RH}$ .**

**H. Environmental Characteristics:**

ITEM	Specification	Test Method
1 Inductance	As SPEC.	Measuring equipment and fixture: HP4287 + Agilent 16196C
2 Insulation Resistance	>1000MΩ	<b>MIL-STD-202F Method 302</b> Apply 100V <sub>ac</sub> for 1 minute
3 Damp Heat with Load	$\Delta L \leq 10\%$	<b>MIL-STD-202F Method 103B</b> 40±2°C, 90~95% R.H. Max. working voltage for 1000 hrs with 1.5 hrs "ON" and 0.5 hrs "OFF"
4 Bending Strength	As SPEC.	<b>JIS-C-5201-1 6.1.4</b> Bending Amplitude 3mm for 10 seconds
5 Solder-ability	95% min coverage	<b>MIL-STD-202F Method 208H</b> 245±5°C for 3 seconds
6 Resistance to Soldering Heat	$\Delta L \leq 10\%$	<b>MIL-STD-202F Method 210E</b> 260±5°C for 10 seconds
7 Dielectric Withstand Voltage	>100V	<b>MIL-STD-202F Method 301.</b> Apply 100VA (rms) for 1minute.
8 High Temperature Exposure	$\Delta L \leq 10\%$	<b>JIS-C-5201-1-7.2</b> 85°C ± 2°C, 1000 +48/-0 hours
9 Low Temperature Storage	$\Delta L \leq 10\%$	<b>JIS-C-5201-1-7.1</b> -40°C ± 3°C, 1000 +48/-0 hours
10 Temperature Cycle	$\Delta L \leq 10\%$	<b>JIS-C-5201-1-7.4</b> -40/RT/85/RT, 10 cycles

- Storage Temperature: 25±3°C; Humidity < 80% RH

**J. Solder Profile:**

